## 高背圧下 PLD により作製した高移動度 In2O3 薄膜を活性層とする TFT

Thin Film Transistors with High-Mobility In<sub>2</sub>O<sub>3</sub> Thin Films

that Fabricated under High-Base Pressure as Active Layers

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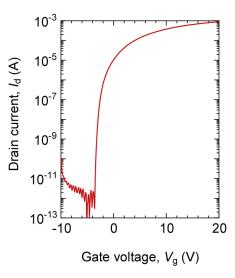
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Very recently, we found that polycrystalline In<sub>2</sub>O<sub>3</sub> films fabricated by pulsed laser deposition (PLD) under relatively high base pressures  $(1.0 \times 10^{-3} \text{ Pa})$  showed extremely high Hall mobility (112.5 cm<sup>2</sup> V<sup>-1</sup> s<sup>-1</sup>) after annealing at 200 °C in vacuum.<sup>[1]</sup> Like previous report by Magari *et al.*<sup>[2]</sup>, hydrogen incorporation might occur and suppress the crystallization at room temperature, and abnormal grain growth occurred when the films were annealed at 200 °C. In this study, we fabricated thin film transistors (TFTs) using the high-mobility In<sub>2</sub>O<sub>3</sub> films as the active channel. First, a 100-nm-thick AlO<sub>x</sub> gate insulator (70.8 nF cm<sup>-2</sup>) was deposited on ITO-coated alkali-free glass substrate (Corning<sup>®</sup> EAGLE XG<sup>®</sup>) by atomic layer deposition. Then In<sub>2</sub>O<sub>3</sub> channel layer with different thickness (5–50 nm) was deposited by PLD through a stencil mask at room temperature. The base pressure was kept at 1.0



**Figure** | Typical transfer characteristic curve of the In<sub>2</sub>O<sub>3</sub>-TFT ( $L = 200 \ \mu\text{m}$ ,  $W = 400 \ \mu\text{m}$ ). Applied drain voltage is 5 V. The field effect mobility ( $\mu_{\text{FE}}$ ) is ~80 cm<sup>2</sup> V<sup>-1</sup> s<sup>-1</sup>.

× 10<sup>-3</sup> Pa while oxygen pressure was kept at 3 Pa during the deposition. After that, 100-nm-thick ITO films that served as source and drain electrodes were deposited by PLD through a stencil mask. Finally, the films were annealed at 250–350 °C for 30 min in air. **Figure** shows typical transfer characteristic curve of the resultant TFT with 5-nm-thick In<sub>2</sub>O<sub>3</sub> channel layer. The field effect mobility ( $\mu_{FE}$ ) was ~80 cm<sup>2</sup> V<sup>-1</sup> s<sup>-1</sup>. Although the  $\mu_{FE}$  is lower than that demonstrated by Magari *et al.* ( $\mu_{FE} = 139 \text{ cm}^2 \text{ V}^{-1} \text{ s}^{-1}$ ), we believe that the  $\mu_{FE}$  would be improved by further optimization of base pressure of PLD chamber. In the presentation, we will show the results of electric field thermopower modulation analyses of the effective thickness as well.

## References

[1] 曲ら, 第70回 応用物理学会 春季学術講演会, 上智大学 2023.3.15-18
[2] Y. Magari *et al.*, *Nat. Commun.* 13, 1078 (2022).